

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	8	("5731046"   "6067368"   "6578436"   "6579833").PN. OR ("6960790").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/17 05:51
L20	8	("5679833"   "5731046"   "5828773"   "5862248"   "6067368"   "6578436"   "6579833"   "6960790").PN. OR ("7235853").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/17 06:10
L21	2	("6759745").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/17 06:28
L22	5	@ad<="20021209" and encapsulat\$3 same ("fingerprint sensor" or "touch sensor") with thick\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 06:59
L23	2	@ad<="20021209" and ("fingerprint sensor" or "touch sensor") with (chip or "IC" or die) with thick\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:00
L24	57	@ad<="20021209" and packag\$3 with thickness same (sensitive or sensor or touch) with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:01
L25	2	@ad<="20021209" and packag\$3 with thickness with "inch" same (sensitive or sensor or touch) with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:04
L26	862	@ad<="20021209" and packag\$3 with thickness with "inch"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:04
L27	37	@ad<="20021209" and package with thickness with "inch" same die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:05
S1	2	"20040056338"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:03
S2	3	"6639308"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 09:40

S3	1	"6388336".PN.	USPAT	OR	OFF	2004/10/06 09:45
S4	2809	@ad<="19991216" and (257/666).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S5	238	@ad<="19991216" and (257/672).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S6	1553	@ad<="19991216" and (257/676).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S7	673	@ad<="19991216" and (257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S8	1127	@ad<="19991216" and (257/692).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S9	200	@ad<="19991216" and (438/111).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:06
S10	570	@ad<="19991216" and (438/123).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:06
S11	348	@ad<="19991216" and (257/670).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S12	571	@ad<="19991216" and (257/677).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S13	99	@ad<="19991216" and (257/e23.141).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:10
S14	915	@ad<="19991216" and (257/e23.043).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11
S15	52	@ad<="19991216" and (257/e23.045).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11

S16	24	@ad<="19991216" and (257/e23.05).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11
S17	330	@ad<="19991216" and (257/e23.052).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:12
S18	303	@ad<="19991216" and (257/e23.066).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:12
S19	83	@ad<="19991216" and (257/666).ccls. and 'lead frame' and 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:13
S20	559	@ad<="19991216" and (361/813).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:21
S21	76	@ad<="19991216" and 'lead frame' and 'tie bar' and 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:58
S22	2	@ad<="19991216" and 'chip' same 'lead frame' and 'various' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:01
S23	2	("6239487").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/06 11:00
S24	2	@ad<="19991216" and 'lead frame' and 'various' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:37
S25	164	@ad<="19991216" and 'lead frame' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S26	57	@ad<="19991216" and 'lead frame' same 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S27	37	@ad<="19991216" and 'semiconductor package' and 'lead frame' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 08:58

S28	23	@ad<="19991216" and 'lead frame' same 'variable' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S29	108	@ad<="19991216" and 'lead frame' with 'flange'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S30	120	@ad<="19991216" and 'semiconductor package' and 'leadframe' with 'step'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:29
S31	1	@ad<="19991216" and 'leadframe' and 'various' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:37
S32	31	@ad<="19991216" and 'leadframe' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S33	11	@ad<="19991216" and 'leadframe' same 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S34	5	@ad<="19991216" and 'leadframe' same 'variable' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S35	11	@ad<="19991216" and 'leadframe' with 'flange'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:45
S70	2811	@ad<="19991216" and (257/666).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S71	238	@ad<="19991216" and (257/672).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S72	1554	@ad<="19991216" and (257/676).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S73	674	@ad<="19991216" and (257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S74	1128	@ad<="19991216" and (257/692).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22

S75	349	@ad<="19991216" and (257/670).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S76	571	@ad<="19991216" and (257/677).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S94	2	@ad<="20001013" and 'lead-on-chip' and 'tiebar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:22
S101	1	"5357139".PN.	USPAT; USOCR	OR	ON	2005/01/05 12:16
S102	44	@ad<="20001013" and 'lead-on-chip' and 'tie bar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:22
S107	782	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:46
S108	10	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die' and 'sealing material'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 10:06
S110	66	@ad<="19991216" and 'lead frame' and 'tie bar' and 'LOC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 10:01
S111	11	@ad<="19991216" and 'lead frame' and 'tie bar' and 'COL'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 10:01
S112	240	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die' and 'sealing'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 10:06
S113	19354	@ad<="20040113" and (257/690).ccls. or (257/730).ccls. or (257/787).ccls. or (257/686).ccls. or (257/783).ccls. or (257/777).ccls. or (257/696).ccls. or (257/676).ccls. or (257/707).ccls. or (257/675).ccls. or (257/666).ccls. (257/692).ccls. or (257/711).ccls. (257/784).ccls. or (257/731).ccls. or (257/106).ccls. or (438/106).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:34

S114	6	@ad<="20040113" and 'chip' and 'tie bars' and 'chip paddle' and 'lead' and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:42
S115	22	@ad<="20040113" and 'chip' and 'tie bars' and 'chip pad' and 'lead' and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:35
S116	188	@ad<="20040113" and 'chip' and 'tie bar' and ('chip paddle' or 'die pad') and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:51
S134	45	(US-20040056338-\$).did. or (US-3902148-\$ or US-3909838-\$ or US-5065223-\$ or US-5424577-\$ or US-5559366-\$ or US-5648682-\$ or US-5763829-\$ or US-5786639-\$ or US-5818105-\$ or US-5834831-\$ or US-5894107-\$ or US-5923092-\$ or US-5929513-\$ or US-5929514-\$ or US-6002181-\$ or US-6020625-\$ or US-6040620-\$ or US-6046504-\$ or US-6081029-\$ or US-6104095-\$ or US-6157074-\$ or US-6197615-\$ or US-6198171-\$ or US-6229200-\$ or US-6239487-\$ or US-6242287-\$).did. or (US-6246113-\$ or US-6256200-\$ or US-6268646-\$ or US-6291881-\$ or US-6307755-\$ or US-6335548-\$ or US-6355502-\$ or US-6388336-\$ or US-6410979-\$ or US-6414385-\$ or US-6448633-\$ or US-6455348-\$ or US-6525406-\$ or US-6559525-\$ or US-6639308-\$ or US-6838754-\$).did. or (WO-8705153-\$ or JP-11260987-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2007/11/16 17:32
S142	4	((("6552419") or ("6313528")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/16 17:51
S143	55	@ad<="20021209" and ("flip-chip" or "flip chip") and ("lead frame" or leadframe) and (encapsulat\$3 or resin) and solder with "metal bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 17:54

S145	316	@ad<="20021209" and "BGA" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 17:59
S146	296	@ad<="20021209" and "BGA" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe) and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 18:00
S147	62	("5492266"   "5535936"   "5542601"   "5849608"   "6297142"   "6337522").PN. OR ("6482680").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 18:06
S148	7	("20020031902"   "20040169275"   "6482680"   "6507120"   "6577012"   "6597059"   "6661087").PN. OR ("7169641").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 18:08
S149	655	@ad<="20021209" and ("flip-chip" or "flip chip") with ("lead frame" or leadframe)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 18:44
S150	513	@ad<="20021209" and "flip chip" with "lead frame"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 18:50
S151	307	@ad<="20021209" and "flip chip" with "lead frame" and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 18:51
S152	22	("3670396"   "4010885"   "4605833"   "4867715"   "5252853"   "5463245"   "5789803"   "5946590"   "6008532"   "6150724"   "6172419"   "6214642"   "6225144"   "6258622"   "6348399"   "6350668"   "6369448"   "6376352"   "6408510"   "6410415"   "6441488").PN. OR ("6828220").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 18:53
S153	812	@ad<="20021209" and "lead-on-chip"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:03
S154	115	@ad<="20021209" and "lead-on-chip" same encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:03

S155	29	@ad<="20021209" and "lead-on-chip" same encapsulant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:04
S156	1	@ad<="20021209" and "lead-on-chip" same sensor with chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:04
S157	4	@ad<="20021209" and "lead-on-chip" and sensor with chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:04
S158	369	@ad<="20021209" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:06
S159	233	@ad<="20021209" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die) with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:07
S160	47	@ad<="20021209" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die) same step\$3 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:07
S161	458	@ad<="20021209" and ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die) same step\$3 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:14
S162	326	@ad<="20021209" and ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die) with step\$3 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:15
S163	130	("3833984"   "3851221"   "4530152"   "4567643"   "4707724"   "4730232"   "4756080"   "4763188"   "4812896"   "4982265"   "4996587"   "5012323"   "5025306"   "5040052"   "5041902"   "5138438"   "5140404"   "5157480"   "5165067"   "5172213"   "5172214"   "5198888"   "5200362"   "5200809"   "5214845"   "5216278"   "5221642"   "5229647"   "5258094"   "5273938"	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 21:17



		"5277972"   "5278446"   "5279029"   "5291061"   "5323060"   "5332864"   "5334875"   "5336931"   "5343076"   "5347429"   "5406124"   "5422435"   "5424576"   "5426563"   "5432729"   "5435057"   "5463253"   "5473196"   "5495394"   "5495398"   "5502289"   "5514907"   "5521429"   "5569625"   "5581498"   "5587341"   "5604376"   "5608267"   "5614766"   "5637536"   "5637912"   "5639990"   "5640047"   "5641997"   "5646831"   "5650663"   "5682062"   "5683806"   "5689135"   "5696031"   "5696666"   "5701034"   "5710064"   "5715147"   "5721452"   "5736432"   "5739581"   "5776798"   "5783861"   "5783870"   "5793108"   "5798014"   "5815372"   "5835988"   "5859471"   "5861666"   "5866939"   "5872025"   "5877043"   "5885849"   "5886412"   "5894108"   "5917242"   "5952611"   "5973403"   "5977613"   "5977630"   "5981314"   "6001671"   "6005778"   "6025640"   "6051886"   "6057598"   "6072243"   "6080264"   "6130115"   "6130473"   "6133637"   "6143981"   "6184463"   "6198171"   "6214641"   "6225146"   "6229200"   "6235554"   "6242281"   "6281568"   "6326696"   "6414385"   "6476474"   "6559525"   "RE36613"). PN. OR ("6759737").URPN.				
S164	787	@ad<="20021209" and ("lead frame" or leadframe) same (chip or "IC" or die) with step\$3 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:19
S165	45	@ad<="20021209" and packag\$3 same stimulus with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:22

S166	268	@ad<="20021209" and packag\$3 same touch with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:24
S167	2	@ad<="20021209" and packag\$3 same touch with sensitive with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:24
S168	912	@ad<="20021209" and packag\$3 same sensitive with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:25
S169	699	@ad<="20021209" and touch with surface with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:29
S170	276	@ad<="20021209" and ("fingerprint sensor" or "touch sensor") with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:33
S172	14	@ad<="20021209" and encapsulat\$3 same ("fingerprint sensor" or "touch sensor") with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:33

**11/17/07 10:34:43 AM**

**C:\Documents and Settings\tle10\My Documents\EAST\Workspaces\Packaging, Flip Chip, BGA, Solder Ball, Bonding Pad, Testing\10536859 Advance Interconnect lead frame 257.wsp**